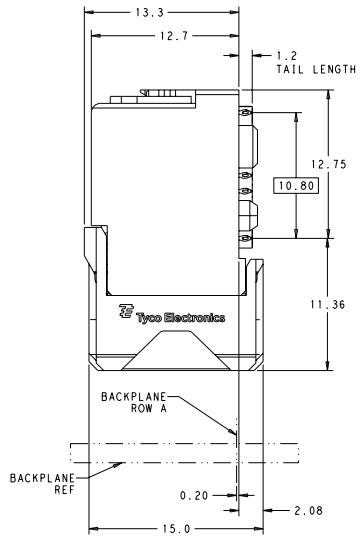
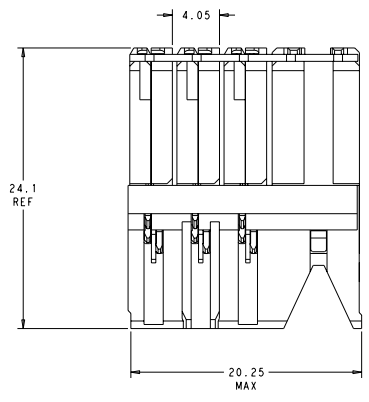
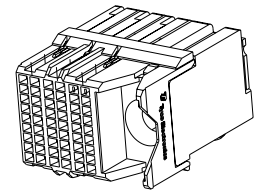


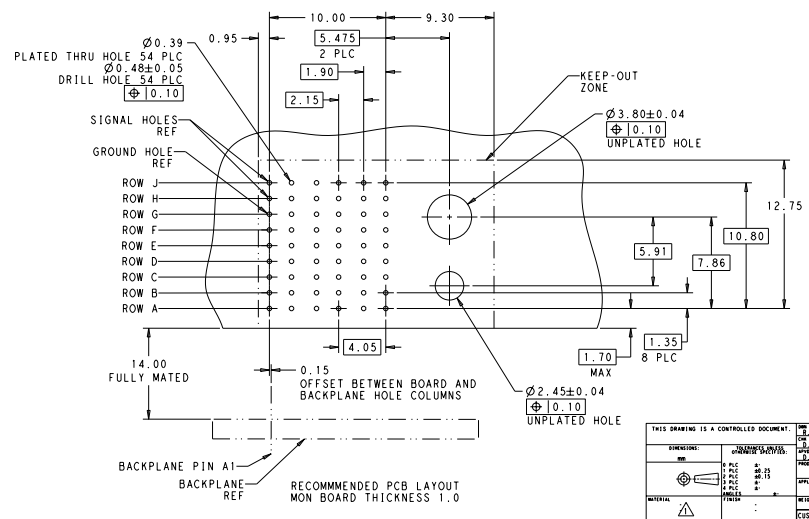
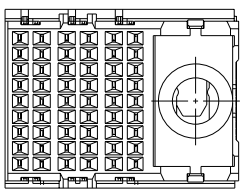
REV	DATE	DESCRIPTION	BY	CHK	APP
A	00	RELEASED			



- △ MATERIAL:
HOUSING: LCP, GLASS FILLED, UL94V-0
TERMINALS: HIGH PERFORMANCE COPPER ALLOY
- △ FINISH:
30µ" SELECTIVE GOLD IN CONTACT AREA, SELECTIVE TIN
ON PCB TAILS, NICKEL OVERALL
- 3. EACH SIGNAL WAFER CONTAINS 2 COLUMNS OF TERMINALS
- △ FINISH:
30µ" SELECTIVE GOLD IN CONTACT AREA, SELECTIVE TIN-LEAD
ON PCB TAILS, NICKEL OVERALL



SCALE 4:1



△	2132423-5
△	2132423-1
FINISH	PART NUMBER

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APACCT, 3 PR., 6 COL., DAUGHTERCARD, RIGHT GUIDED SIGNAL MODULE 0.39 EYELET, ORTHOGONAL

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